



## Product Change Notification / RMES-15ZREP293

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### Date:

15-Jan-2021

### Product Category:

Memory

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 3379.002 and CCB 3280.001 Final Notice: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.

### Affected CPNs:

[RMES-15ZREP293\\_Affected\\_CPN\\_01152021.pdf](#)

[RMES-15ZREP293\\_Affected\\_CPN\\_01152021.csv](#)

### Notification Text:

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.

### Pre Change:

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700LS mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock.**or** Assembled at ASSH assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900GC die attach and CEL-9240HF10AK mold compound material with Matte tin lead plating in 93 x 93 mils paddle size without lead lock.**and**

Tested at ASSH or ANAP Final Test site.

**Post Change:**

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700LS mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock. **or**

Assembled at ASSH assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900GC die attach and CEL-9240HF10AK mold compound material with Matte tin lead plating in 93 x 93 mils paddle size without lead lock.

**or** Assembled at MTAI assembly site using gold (Au) bond wire, 8390A die attach and G600V mold compound material with Matte tin lead plating in 90 x 90 mils paddle size with lead lock. **and**

Tested at ASSH, ANAP or MTAI Final Test site.

**Pre and Post Change Summary:**

		Pre Change		Post Change		
<b>Assembly Site</b>		Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Microchip Technology Thailand (HQ) (MTAI)
<b>Wire material</b>		PdCu	CuPdAu	PdCu	CuPdAu	Au
<b>Die attach material</b>		8290	EN-4900GC	8290	EN-4900GC	8390A
<b>Molding compound material</b>		G700LS	CEL-9240HF10AK	G700LS	CEL-9240HF10AK	G600V
<b>Lead frame material</b>		CDA194	CDA194	CDA194	CDA194	CDA194
<b>Paddle size</b>		60 x 60 mils	93 x 93 mils	60 x 60 mils	93 x 93 mils	90 x 90 mils
<b>Lead Lock</b>		No	No	No	No	Yes
<b>Lead Plating</b>		NiPdAu	Matte tin	NiPdAu	Matte tin	Matte Tin
		Pre Change		Post Change		
<b>Final Test Site</b>		ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)	Amkor Technology Philippines (P1/P2), INC. (ANAP)	Microchip Technology Thailand (MTAI)
<b>Base Quantity Multiple (BQM)</b>	<b>Tube</b>	100	100	100	100	100
	<b>Tape and Reel</b>	4000	4000	4000	4000	4000
<b>Pin1 Orientation</b>	<b>Tube</b>	Pin 1 side (Black)	Not Applicable	Pin 1 side (Black)	Not Applicable	Pin 1 side (White)
	<b>Tape and Reel</b>	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1	Quadrant 1
<b>Tube</b>		Minor dimensional changes – see attachment				

Carrier Tape	No change
Cover Tape	Minor dimensional changes – see attachment
Plastic Reel	Minor dimensional changes – see attachment
Packing Procedure for Tube and Tape & Reel	See attachment

**Impacts to Data Sheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying MTAI as an additional assembly and final test site

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** February 15, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	January 2021					February 2021				
	01	02	03	04	05	06	07	08	09	10
Qual Report Availability			X							
Final PCN Issue Date			X							
Estimated First Ship Date								X		

**Method to Identify Change:** Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report. PCN\_RMES-15ZREP293\_Qual\_Report – Assembly sitePCN\_RMES-15ZREP293\_Qual\_Report – Final Test site

**Revision History: January 15, 2021:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_RMES-15ZREP293\\_Qual\\_Report - Assembly Site.pdf](#)  
[PCN\\_RMES-15ZREP293\\_Qual\\_Report - Final Test.pdf](#)  
[PCN\\_RMES-15ZREP293\\_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

AT24C01D-SSHM-B  
AT24C02D-SSHM-B  
AT24C01D-SSHM-T  
AT24C02D-SSHM-T  
AT24C04D-SSHM-B  
AT24C04D-SSHM-T  
AT24C08D-SSHM-B  
AT24C08D-SSHM-T  
AT24C16D-SSHM-B  
AT24C16D-SSHM-T  
AT24C32E-SSHM-B  
AT24C32E-SSHM-T



**MICROCHIP**

**QUALIFICATION REPORT SUMMARY**  
RELIABILITY LABORATORY

**PCN #: RMES-15ZREP293**

**Date:**  
**December 04, 2020**

**Qualification of MTAI as an additional assembly site for selected  
Atmel AT24C0xD, AT24C16D and AT24C32E device families available  
in 8L SOIC packages.**



## MICROCHIP PACKAGE QUALIFICATION REPORT

<b>Purpose</b>	Qualification of MTAI as an additional assembly site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.
<b>CN</b>	ES220208
<b>QUAL ID</b>	Q18136 Rev. A
<b>MP CODE</b>	365S6QC2XA00
<b>Part No.</b>	25LC640AT-H/SN
<b>Bonding No.</b>	BDE-004738 REV. 03
<b>CCB No.</b>	3379 and 3379.001
<b><u>Package</u></b>	
<b>Type</b>	8L SOIC
<b>Package size</b>	150 mils
<b><u>Lead Frame</u></b>	
<b>Paddle size</b>	90 x 90 mils
<b>Material</b>	CDA194
<b>Surface</b>	Bare Cu on paddle
<b>Process</b>	Stamped
<b>Lead Lock</b>	Yes
<b>Part Number</b>	10100841
<b>Treatment</b>	Roughened
<b><u>Material</u></b>	
<b>Epoxy</b>	8390A
<b>Wire</b>	Au wire
<b>Mold Compound</b>	G600V
<b>Plating Composition</b>	Matte Tin



# MICROCHIP PACKAGE QUALIFICATION REPORT

## Manufacturing Information:

Assembly Lot No.	Wafer No.	Date Code
MTAI191002659.000	MCS0518466473.300	1823J79
MTAI191003913.000	MCS0518466473.300	1823Q4H
MTAI191003922.000	MCS0518466473.300	1823Q7C

## Result

Pass  Fail  \_\_\_\_\_

8L SOIC (.150") assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.



# PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<b>Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)</b>	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243  ( IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135	0/135	Pass	

<b>Precondition Prior Perform Reliability Tests (At MSL Level 1)</b>	<b>Electrical Test</b> :+25°C,85°C,125°C and 150°C System: NEXTEST_PT	JESD22- A113	693(0)	693	Pass	Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	<b>Electrical Test</b> :+25°C,85°C,125°C and 150°C System: NEXTEST_PT			0/693		

# PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks	
<b>Temp Cycle</b>	<b>Stress Condition:</b> -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22- A104		231		Parts had been pre-conditioned at 260°C	
	<b>Electrical Test:</b> +85°C,125°C and 150°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot	
	<b>Stress Condition:</b> -65°C to +150°C, 2000 Cycles System : TABAI ESPEC TSA-70H			231			
	<b>Electrical Test:</b> +85°C,125°C and 150°C System: NEXTEST_PT		231(0)	0/231	Pass		
<b>UNBIASED-HAST</b>	<b>Stress Condition:</b> +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C	
	<b>Electrical Test:</b> +25°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot	
<b>HAST</b>	<b>Stress Condition:</b> +130°C/85%RH, 96 hrs. <b>Bias Volt:</b> 5.5 Volts System: HAST 6000X	JESD22- A110		231		Parts had been pre-conditioned at 260°C	
	<b>Electrical Test:</b> + 25°C,85°C,125°C and 150°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot	

## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>High Temperature Storage Life</b>	<b>Stress Condition:</b> Bake 175°C, 500 hrs System: SHEL LAB	JESD22- A103		45		45 units
	<b>Electrical Test:</b> +25°C,85°C,125°C and 150°C System: NEXTEST_PT		45(0)	0/45	Pass	
	<b>Stress Condition:</b> Bake 175°C, 1000 hrs System: SHEL LAB			45		45 units
	<b>Electrical Test</b> :+ 25°C,85°C,125°C and 150°C System: NEXTEST_PT		45(0)	0/45	Pass	
<b>Bond Strength Data Assembly</b>	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	

# CCB 3379.002 and 3280.001 Pre and Post Change Summary PCN #: RMES-15ZREP293



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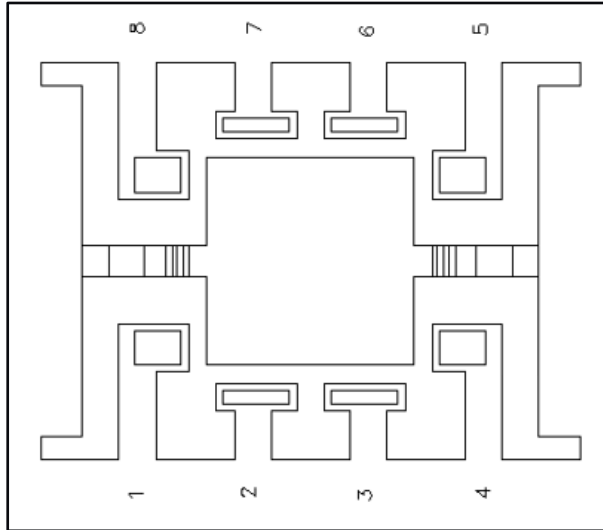
**Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.**



SMART | CONNECTED | SECURE

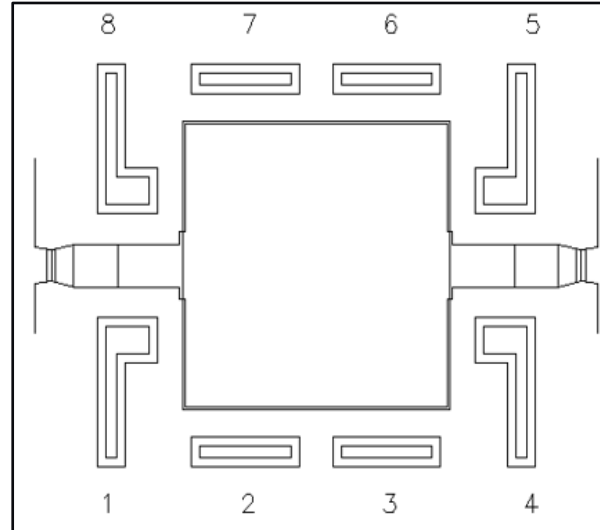
# LEAD FRAME COMPARISON

## ANAP



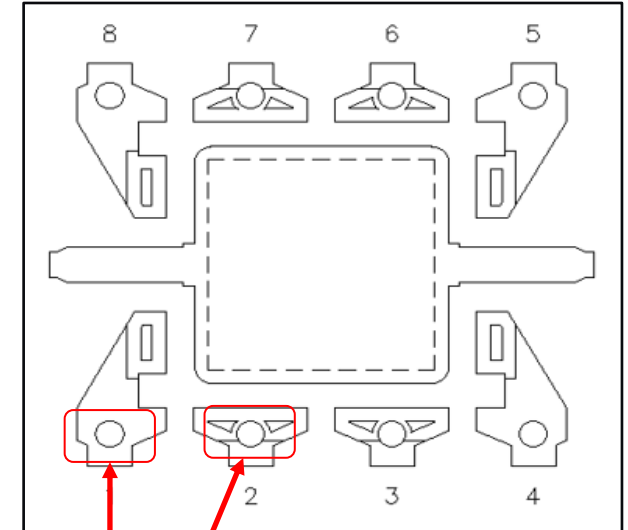
<b>Paddle size</b>	60 x 60 mils
<b>Lead Lock</b>	No
<b>Lead Plating</b>	NiPdAu

## ASSH



<b>Paddle size</b>	93 x 93 mils
<b>Lead Lock</b>	No
<b>Lead Plating</b>	Matte tin

## MTAI

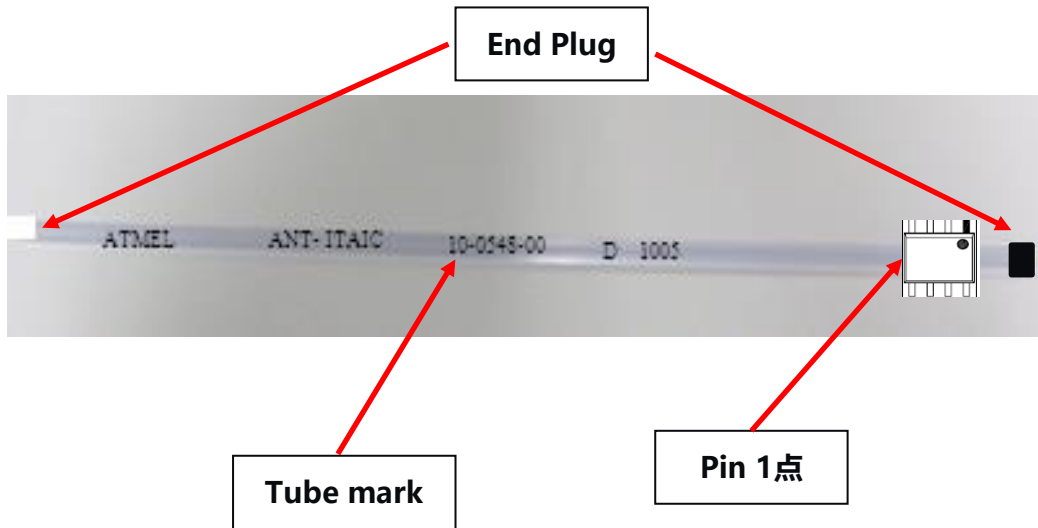


Lead Lock

<b>Paddle size</b>	90 x 90 mils
<b>Lead Lock</b>	Yes
<b>Lead Plating</b>	Matte Tin

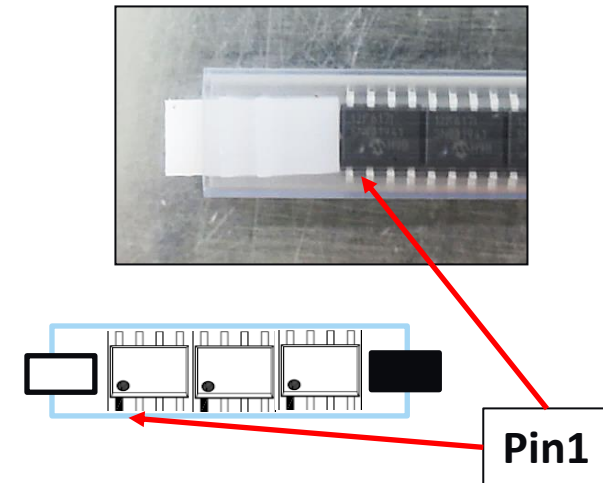
# TUBE BQM AND PIN1 ORIENTATION

## ASSH



Media	Unit/ Tube	Tubes /Bag	Pin 1 Orientation
Tube	100	100	Black end plug

## MTAI

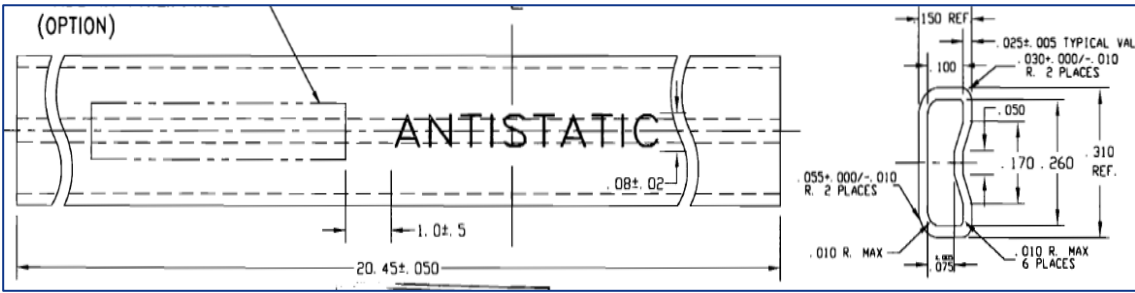
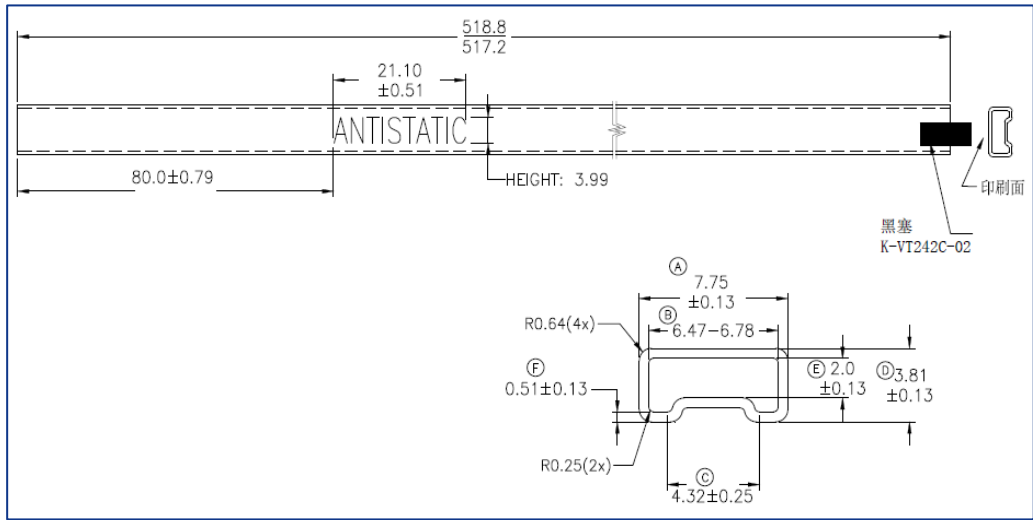


Media	Unit/ Tube	Tubes /Bag	Pin 1 Orientation
Tube	100	100	White end plug

# TUBE DIMENSION – Minor changes

## ASSH






## MTAI



Length	Color
20.00 +/- 0.03 inch (518 +/- 0.8 mm)	Clear

Length	Color
20.50 +/- 0.05 inch (520.7 +/- 1.2 mm)	Clear

# TUBE NON-DRY PACK

ASSH			MTAI																													
																																
SSB	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr style="background-color: #003366; color: white;"> <th>Material</th> <th>Width</th> <th>Length</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">SSB</td> <td style="text-align: center;">254 mm</td> <td style="text-align: center;">762 mm</td> </tr> </tbody> </table>		Material	Width	Length	SSB	254 mm	762 mm	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr style="background-color: #003366; color: white;"> <th>Material</th> <th>Width</th> <th>Length</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">SSB</td> <td style="text-align: center;">160 mm</td> <td style="text-align: center;">650 mm</td> </tr> </tbody> </table>		Material	Width	Length	SSB	160 mm	650 mm																
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Material	Dimension W x L x H (cm)	Number of Bag/carton																														
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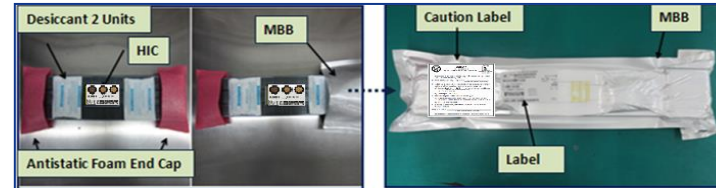
# TUBE DRY PACK

## ASSH

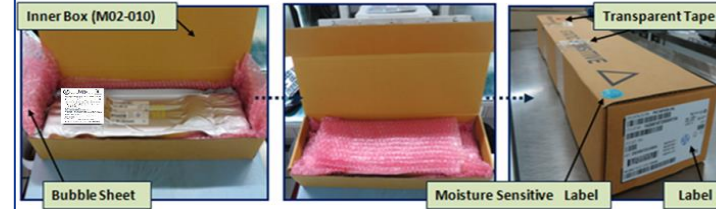
NO DRY PACKING

## MTAI

Material	Width	Length
MBB	160 mm	650 mm



MBB



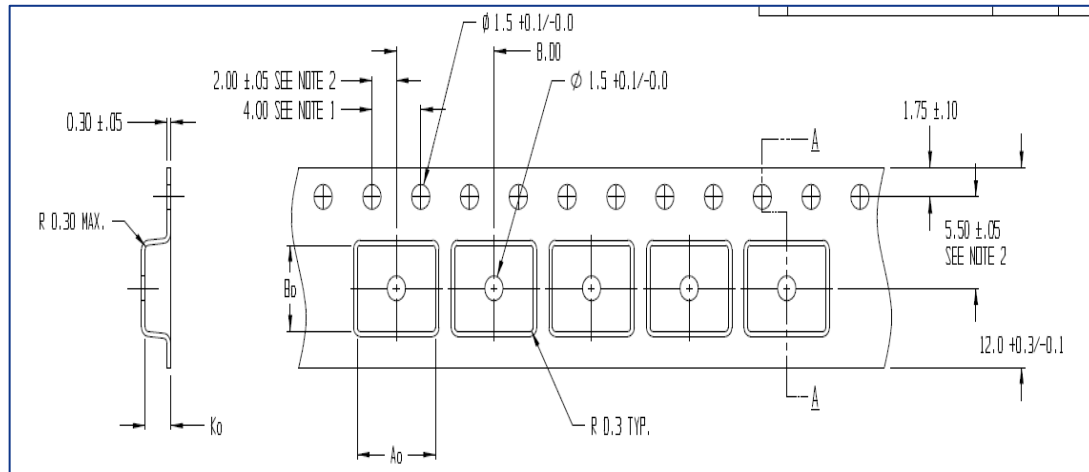
Inner box		Carton		Number of Inner box(es) per carton
Drawing number	Dimension W x L x H (cm)	Drawing number	Dimension W x L x H (cm)	
M02-010	12.9x56.5x8	M01-022 (PP)	15.5x62.0x14.0	1 per 1
		M01-028 (C4)	28x63.5x11	2 per 1
		M01-029 (C6)	28x63.5x15.5	3 per 1
		M01-030 (C8)	28x63.5x20	4 per 1
		M01-040 (S6)	43x59x19	6 per 1

# T/R BQM AND PIN1 ORIENTATION

ASSH			MTAI		
Media	Reel/Bag	Unit/Reel	Media	Reel/Bag	Unit/Reel
T/R	1	4000	T/R	1	4000

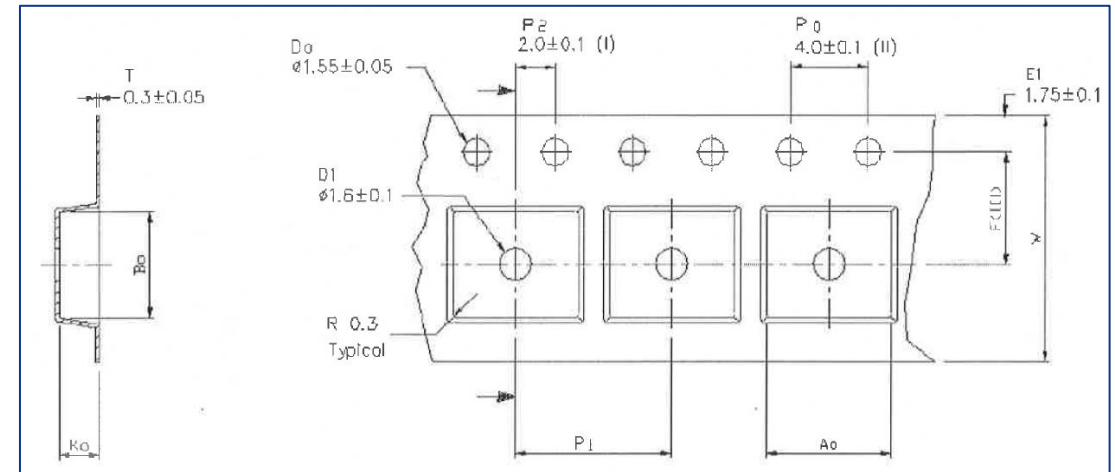
# CARRIER TAPE – No changes

## ASSH



W (mm.) $\pm 0.3$ or Specific	P (mm.) $\pm 0.1$ or Specific	$A_0 \pm 0.1$ or Specific	$B_0 \pm 0.1$ or Specific	$K_0 \pm 0.1$ or Specific	Thickness
12	8	6.40	5.20	2.10	-

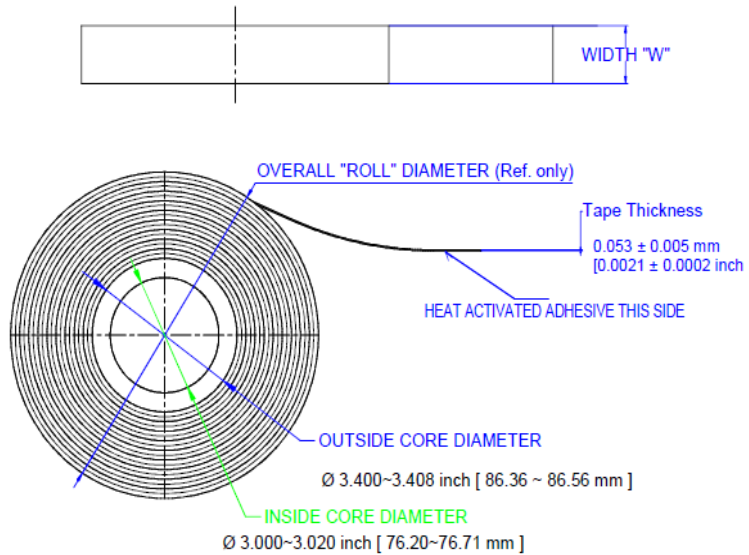
## MTAI



W (mm.) $\pm 0.3$ or Specific	P (mm.) $\pm 0.1$ or Specific	$A_0 \pm 0.1$ or Specific	$B_0 \pm 0.1$ or Specific	$K_0 \pm 0.1$ or Specific	Thickness
12	8	6.40	5.20	2.10	-

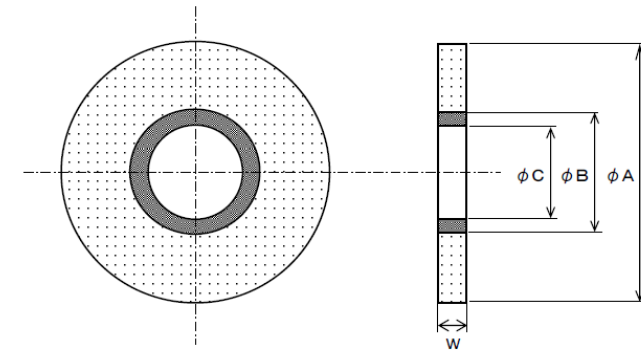
# COVER TAPE – Minor changes

## ASSH

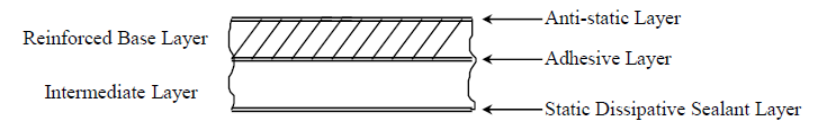


Width	Width "W" (mm)	Thickness (mm)	Sealing Mythology
12 mm	9.2+/-0.07	0.053±0.005	Heat seal

## MTAI



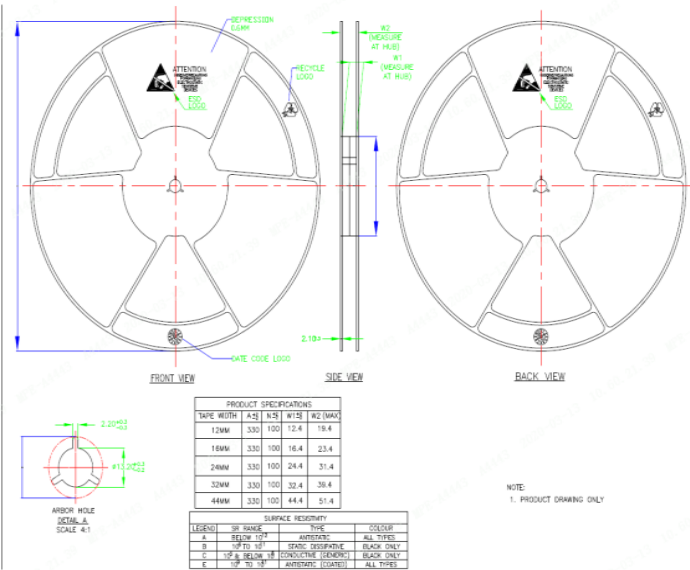
### STRUCTURE



Width	Width "W" (mm)	Thickness (mm)	Sealing Mythology
12 mm	9.05+0.05/-0.15	0.050 ±0.010	Heat seal

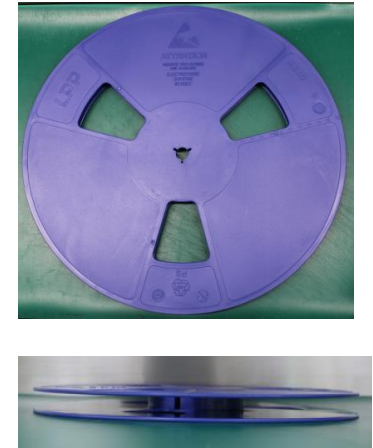
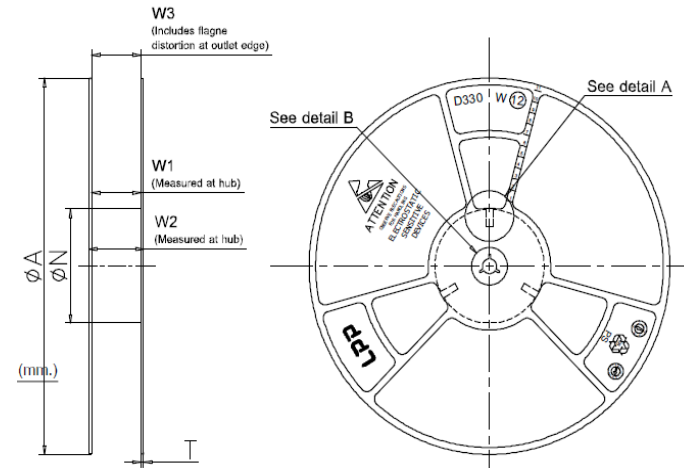
# PLASTIC REEL – Minor changes

## ASSH



Reel Diameter	Hub	W2 Max (mm)	Color
330 mm	4 inch (100mm)	12.40	White

## MTAI



Reel Diameter	Hub	W2 Max (mm)	Color
330 mm	4 inch (100mm)	18.40	Dark Blue

# T/R NON-DRY PACK

## ASSH



Material	WIDTH	LENGTH
SSB	370mm	460mm

SSB

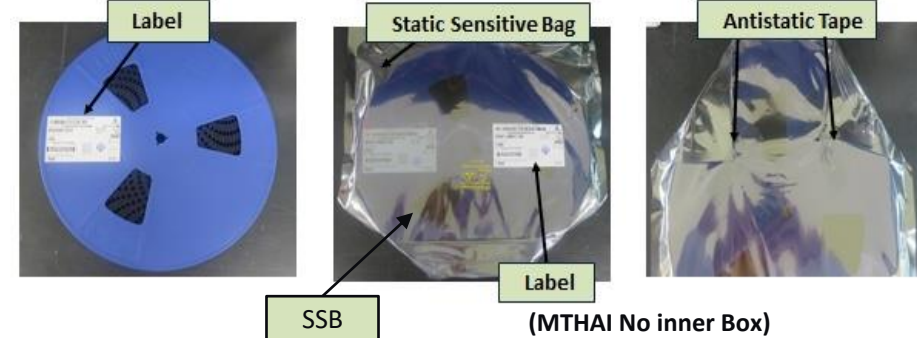


Material	Dimension	Number of reel per carton
	W x L x H (cm)	Reel diameter (D) = 330mm Carrier Tape Width 12mm
Carton	38.4x36.2x38.5	15

## MTAI



Material	WIDTH	LENGTH
SSB	370mm	420mm



Carton	Dimension W x L x H (cm)	Number of reel per carton
		Reel diameter (D) = 330mm Carrier Tape Width 12mm
M01-011 (TT)	36.5x38x39.5	15
M01-012 (B1)	35.5x35.5x2.8	1
M01-013 (B2)	35.5x35.5x4	2
M01-014 (B3)	35.5x35.5x6	3
M01-015 (B8)	35.5x35.5x16.5	8

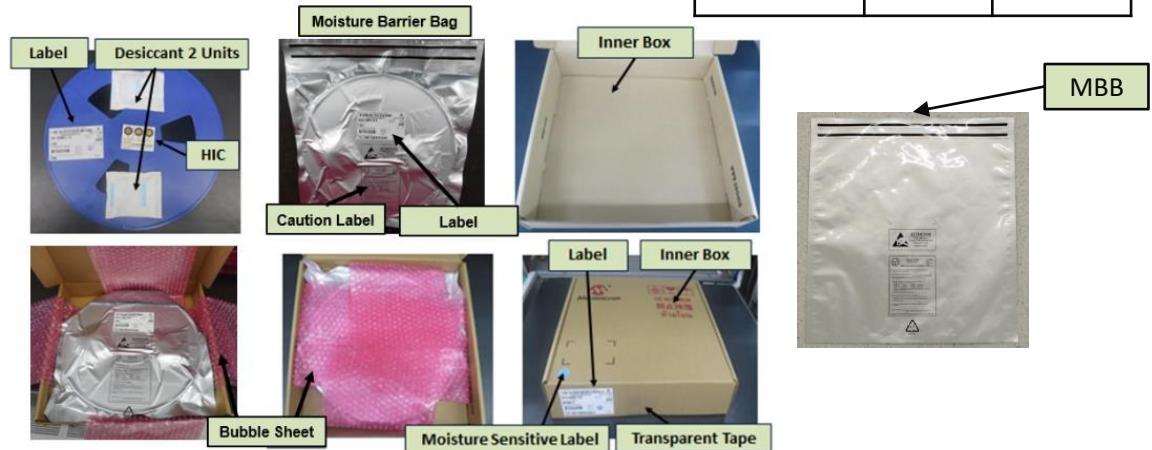
# T/R DRY PACK

## ASSH

NO DRY PACKING

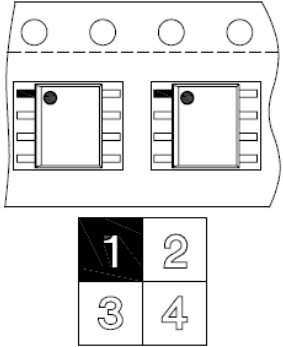
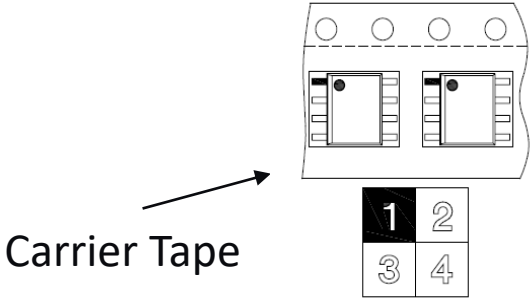
## MTAI

Material	WIDTH	LENGTH
MBB	370mm	420mm



Inner box		Carton		Number of Inner box(es) per carton
Drawing number	Dimension W x L x H (cm)	Drawing number	Dimension W x L x H (cm)	
M02-015 (Small)	37x35.1x5.3	M01-044 (SM)	37.0x38.0x11.0	1 : 1
		M01-045 (S4)	37.0x38.0x22.5	3 : 1
		M01-046 (S5)	37.0x39.0x39.0	6 : 1
		M01-047 (S3)	42.0x66.0x39.0	11 : 1

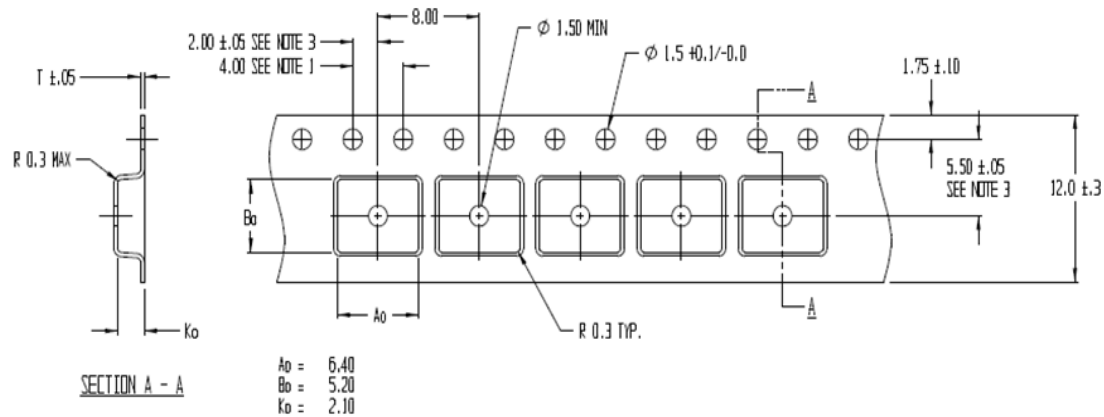
# T/R BQM AND PIN1 ORIENTATION

ANAP			MTAI		
 <p>Quadrant 1</p>			 <p>Quadrant 1</p>		
Media	Reel/Bag	Unit/Reel	Media	Reel/Bag	Unit/Reel
T/R	1	4000	T/R	1	4000



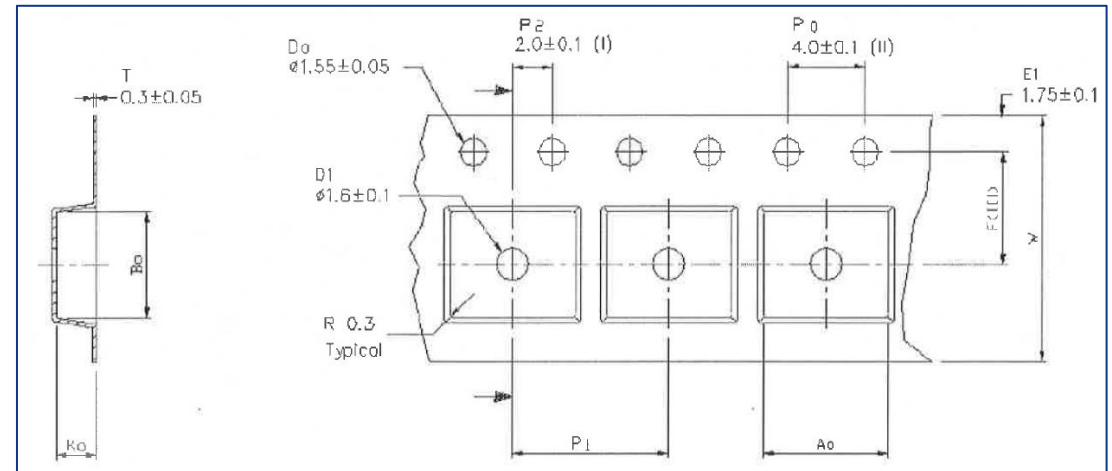
# CARRIER TAPE – No changes

## ANAP



W (mm.) ±0.3 or Specific	P (mm.) ±0.1 or Specific	A <sub>0</sub> ±0.1 or Specific	B <sub>0</sub> ±0.1 or Specific	K <sub>0</sub> ±0.1 or Specific	Thickness
12	8	6.40	5.20	2.10	-

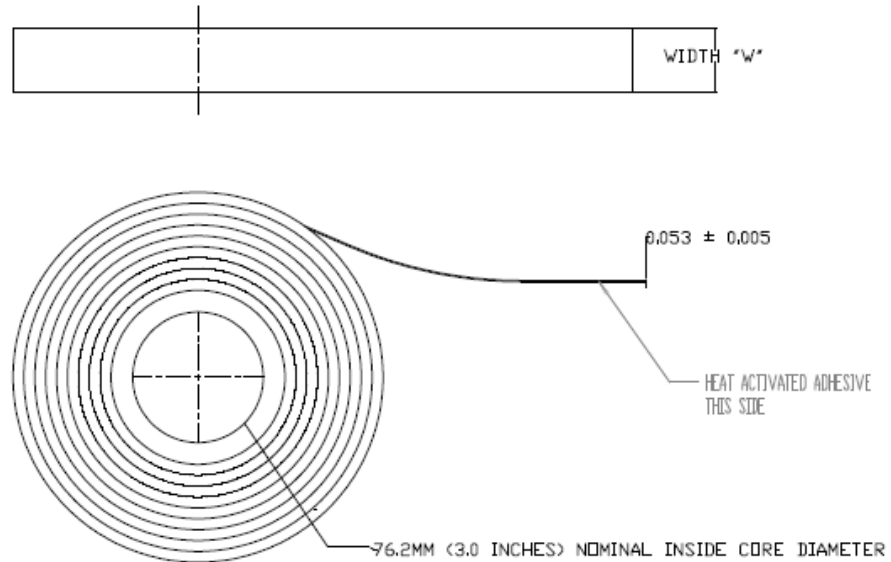
## MTAI



W (mm.) ±0.3 or Specific	P (mm.) ±0.1 or Specific	A <sub>0</sub> ±0.1 or Specific	B <sub>0</sub> ±0.1 or Specific	K <sub>0</sub> ±0.1 or Specific	Thickness
12	8	6.40	5.20	2.10	-

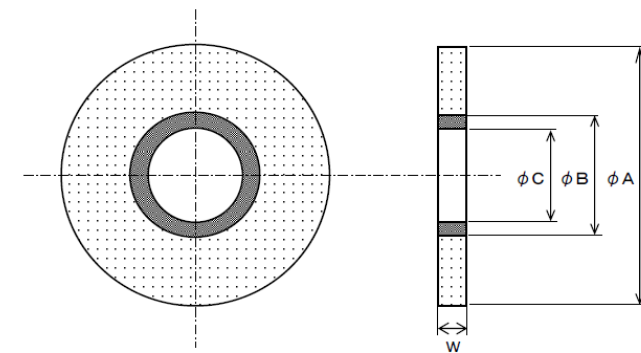
# COVER TAPE – Minor changes

## ANAP

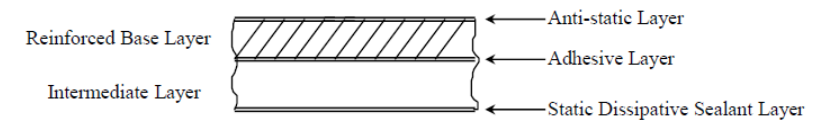


Width	Width "W" (mm)	Thickness (mm)	Sealing Mythology
12 mm	9.2+/-0.010	0.053±0.005	Heat seal

## MTAI



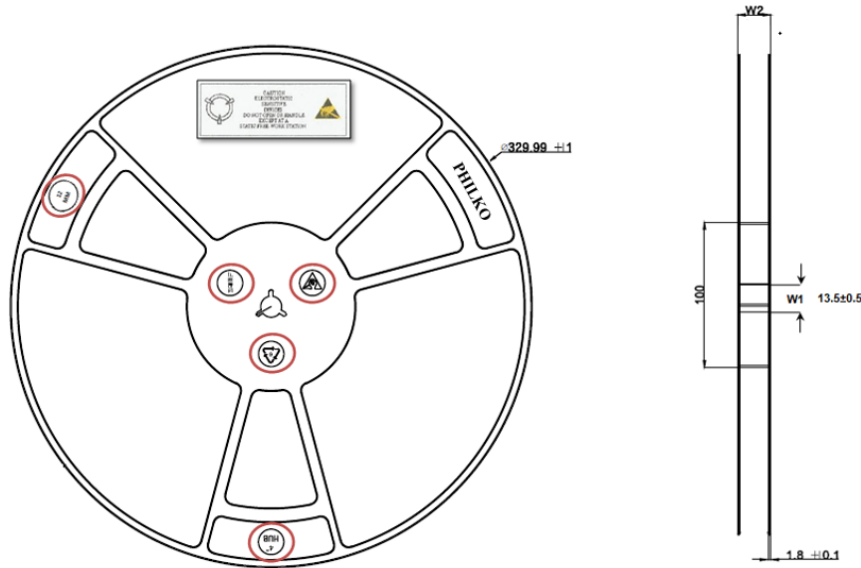
### STRUCTURE



Width	Width "W" (mm)	Thickness (mm)	Sealing Mythology
12 mm	9.05+0.05/-0.15	0.050 ±0.010	Heat seal

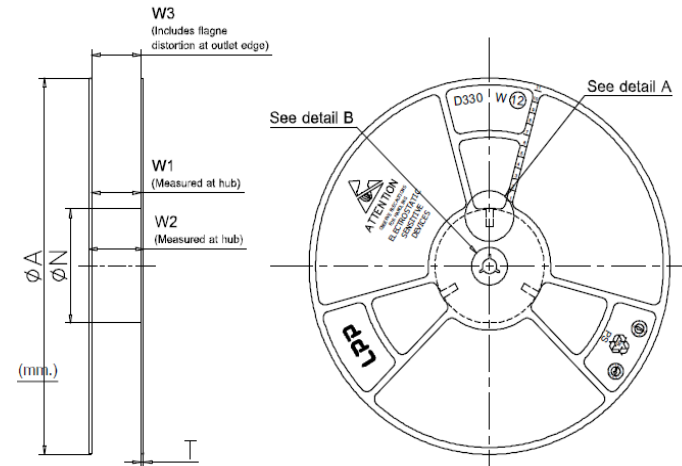
# PLASTIC REEL – Minor changes

## ANAP



Reel Diameter	Hub	W2 Max (mm)	Color
330 mm	4 inch (100mm)	17.50	White

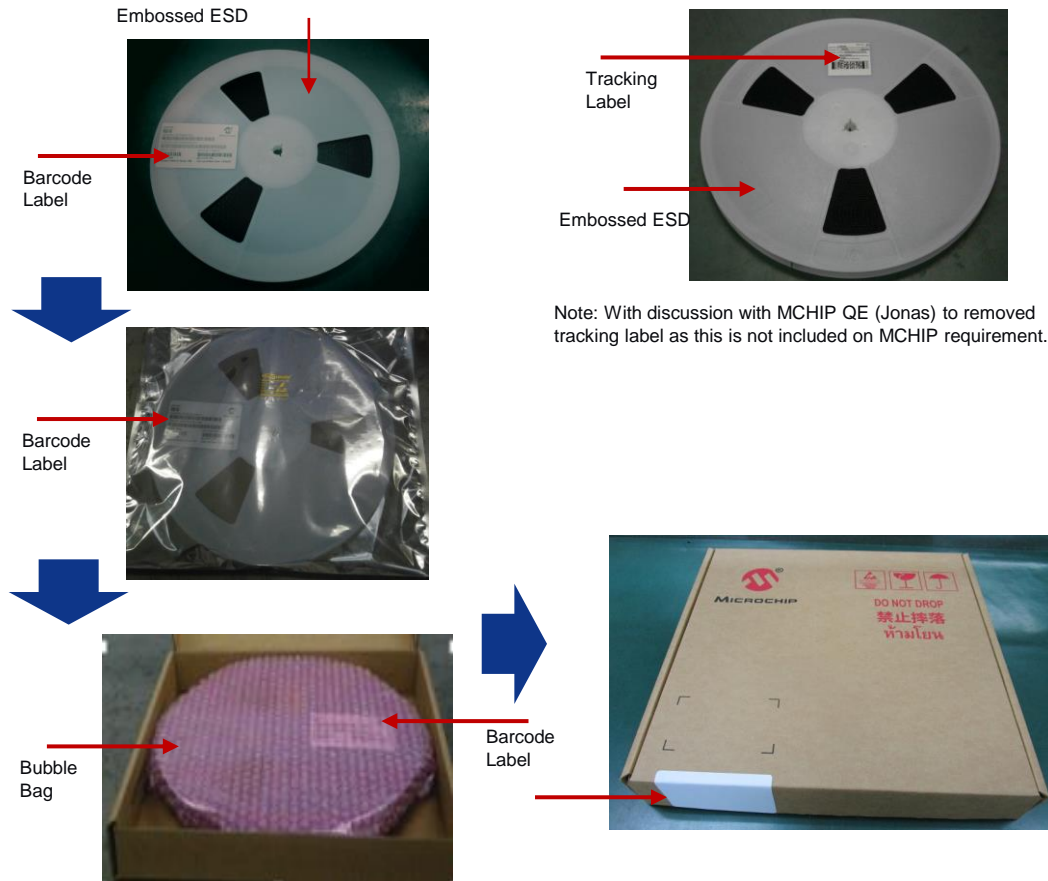
## MTAI



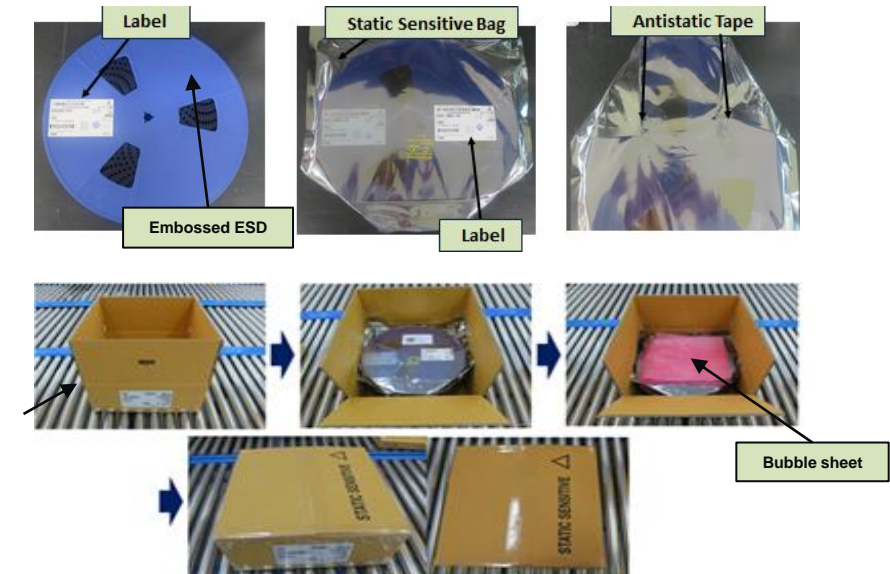
Reel Diameter	Hub	W2 Max (mm)	Color
330 mm	4 inch (100mm)	18.40	Dark Blue

# T/R NON-DRY PACK

## ANAP



## MTAI (MSL 1 – no inner box)



Carton Box	Dimension
M01-012 (B1)	35.5x35.5x2.8 cm (Max 1 Reel)
M01-013 (B2)	35.5x35.5x4 cm (Max 2 Reel)
M01-014 (B3)	35.5x35.5x6 cm (Max 3 Reel)
M01-015 (B8)	35.5x35.5x16.5 cm (Max 8 Reel)
M01-011 (TT)	36.5x38x39.5 cm (Max 15 Reel)



**MICROCHIP**

**QUALIFICATION REPORT SUMMARY**

**PCN #: RMES-15ZREP293**

**Date:  
December 08, 2020**

**Qualification of MTAI as an additional final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.**

**Purpose:** Qualification of MTAI as an additional final test site for selected Atmel AT24C0xD, AT24C16D and AT24C32E device families available in 8L SOIC packages.

**CCB No.:** 3280.001

Test / Evaluation	Test Conditions / Parameters	Results / Remarks
Datalog / Bin Comparison	<ul style="list-style-type: none"> <li>• Compare test numbers, test names, test limit, test sequence, bin assignments &amp; pass/fail results.</li> <li>• Accept if all match or justify the differences</li> </ul>	PASSED
Test stability verification	<ul style="list-style-type: none"> <li>• Test stability verification with TC at -40°C, 25°C and 85°C for singulated</li> <li>• Accept on Cpk &gt; 1.67 or justify/waive parameters if needed</li> </ul>	PASSED
Tester to Tester verification	<ul style="list-style-type: none"> <li>• Perform GR&amp;R. Site 1: Nextest_PT vs Nextest_SSV2t Platform</li> </ul>	PASSED
Yield correlation	<ul style="list-style-type: none"> <li>• Lot Validation, Good vs. rejects comparison. (5000 pcs).</li> <li>• Accept <math>\pm</math> 2% yield difference</li> </ul>	PASSED
Rejects verification	<ul style="list-style-type: none"> <li>• The one failure is marginal fail at 85C with Singulates test program, but on Strip test program the failure get always pass result. Reject rate is 0%.</li> </ul>	PASSED